Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: http://www.renesas.com

April 1st, 2010 Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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HETERO JUNCTION FIELD EFFECT TRANSISTOR

NE32984D

X to Ka BAND SUPER LOW NOISE AMPLIFIER N-CHANNEL HJ-FET

DESCRIPTION

The NE32984D is a Hetero Junction FET that utilizes the hetero junction to create high mobility electrons. Its excellent low noise and high associated gain make it suitable for DBS and another commercial systems.

FEATURES

Super Low Noise Figure & High Associated Gain
 NF = 0.40 dB TYP., Ga = 12.5 dB TYP. at f = 12 GHz

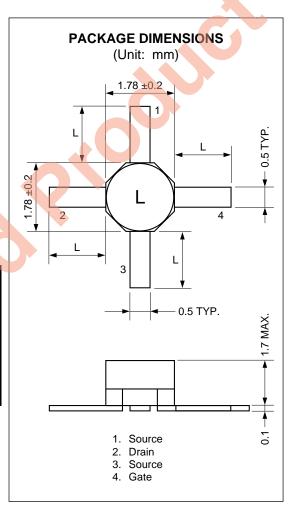
• Gate Length : $L_g \le 0.20 \ \mu m$ • Gate Width : $W_g = 200 \ \mu m$

ORDERING INFORMATION

PART NUMBER	SUPPLYING FORM	LEAD LENGTH	MARKING
NE32984D-SL	STICK	L = 1.7 mm MIN.	7
NE32984D-T1	Tape & reel 1000 pcs./reel	L = 1.0 ± 0.2 mm	
NE32984D-T1A	Tape & reel 5000 pcs./reel	L = 1.0 ± 0.2 mm	

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C)

Vos	4.0	V
Vgs	-3.0	V
lο	IDSS	mΑ
lg	100	μ A
Ptot	165	mW
Tch	150	°C
Tstg	-65 to +150	°C
	Vgs Ib Ig Ptot Tch	Ves -3.0 ID IDSS IG 100 Ptot 165 Tch 150



RECOMMENDED OPERATING CONDITION (TA = 25 °C)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	Unit
Drain to Source Voltage	Vos		2	3	٧
Drain Current	lσ		10	20	mA
Input Power	Pin			0	dBm

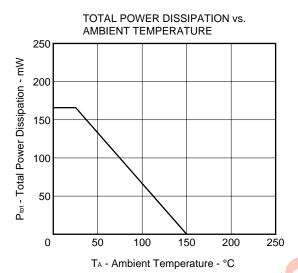
3.0



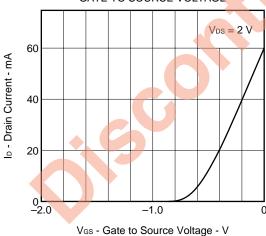
ELECTRICAL CHARACTERISTICS (TA = 25 °C)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Gate to Source Leak Current	Igso		0.5	10	μΑ	V _G S = −3 V
Saturated Drain Current	IDSS	20	60	90	mA	V _{DS} = 2 V, V _{GS} = 0 V
Gate to Source Cutoff Voltage	V _{GS(off)}	-0.2	-0.7	-2.0	V	$V_{DS} = 2 \text{ V}, \text{ ID} = 100 \ \mu\text{A}$
Transconductance	gm	45	60		mS	V _{DS} = 2 V, I _D = 10 mA
Noise Figure	NF		0.40	0.50	dB	V _{DS} = 2 V, I _D = 10 mA, f = 12 GHz
Associated Gain	Ga	11.0	12.5		dB	

TYPICAL CHARACTERISTICS (TA = 25 °C)

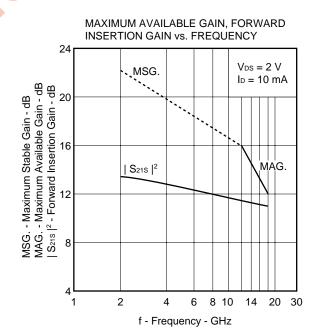


DRAIN CURRENT vs. GATE TO SOURCE VOLTAGE



DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE 100 80 lo - Drain Current - mA $V_{GS} = 0 V$ 60 -0.2 V 40 -0.4 V 20 -0.6 V -0.8 V

1.5 V_{DS} - Drain to Source Voltage - V





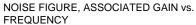
Gain Calculations

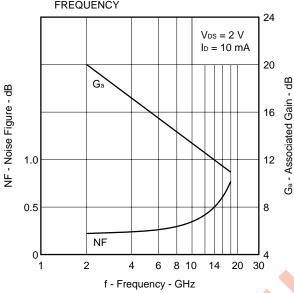
MSG. =
$$\frac{|S_{21}|}{|S_{12}|}$$

$$K = \frac{1 + |\Delta|^2 - |S_{11}|^2 - |S_{22}|^2}{2|S_{12}||S_{21}|}$$

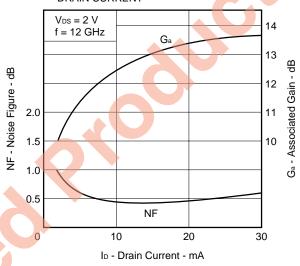
MAG. =
$$\frac{|S_{21}|}{|S_{12}|}$$
 (K $\pm \sqrt{K^2-1}$)

$$\Delta = \mathsf{S}_{11} \bullet \mathsf{S}_{22} - \mathsf{S}_{21} \bullet \mathsf{S}_{12}$$





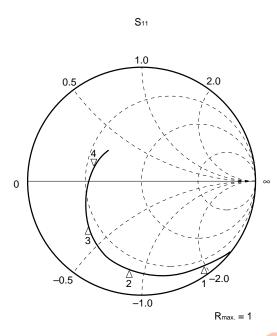
NOISE FIGURE, ASSOCIATED GAIN vs. DRAIN CURRENT

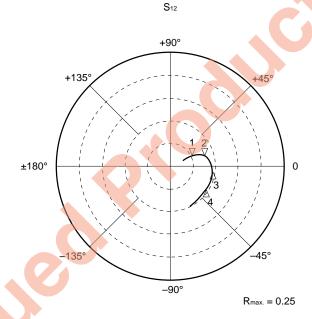


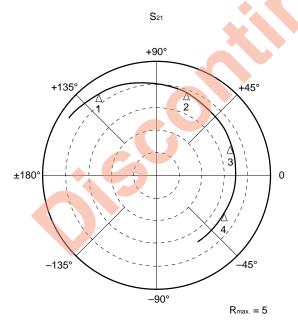
S-PARAMETERS

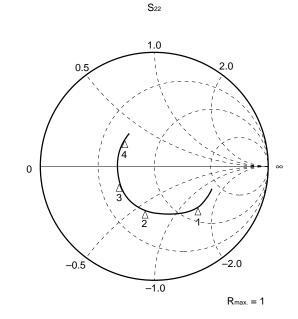
 $V_{DS} = 2 \text{ V}, \text{ ID} = 10 \text{ mA}$ START 2 GHz, STOP 18 GHz, STEP 500 MHz

Marker
1: 4 GHz
2: 8 GHz
3: 12 GHz
4: 16 GHz











S-PARAMETER

MAG. AND ANG. $V_{DS} = 2 V$, $I_{D} = 10 mA$

FREQUENCY		S 11	S	21	S	S ₁₂	Ş	S22
GHz	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.
		(deg.)		(deg.)		(deg.)		(deg.)
2.0	.988	-27.9	4.628	149.5	.028	71.2	.562	-22.6
2.5	.959	-33.1	4.521	142.2	.034	65.1	.553	-28.6
3.0	.959	-39.3	4.512	135.4	.040	60.1	.536	-33.5
3.5	.956	-46.8	4.513	128.9	.045	56.8	.517	-40.7
4.0	.936	-52.4	4.497	121.5	.050	51.2	.505	-46.0
4.5	.913	-59.9	4.429	114.6	.055	48.4	.480	-53.0
5.0	.913	-66.8	4.335	106.9	.060	43.3	.464	-58.3
5.5	.874	-71.3	4.269	100.0	.064	39.3	.450	-64.2
6.0	.846	-78.3	4.135	92.4	.069	35.6	.423	-73.4
6.5	.843	-85.0	4.101	85.9	.071	31.7	.417	-78.6
7.0	.800	-89.4	4.006	80.1	.075	27.5	.404	-85.1
7.5	.779	-94.5	3.889	74.0	.077	23.5	.384	-92.7
8.0	.782	-98.7	3.830	67.3	.079	21.8	.374	-98.5
8.5	.744	-105.5	3.809	62.1	.079	17.8	.367	-104.8
9.0	.723	-108.5	3.695	55.3	.082	14.5	.358	-111.6
9.5	.736	-115.0	3.746	49.7	.084	12.7	.349	-118.1
10.0	.698	-120.1	3.654	43.7	.085	7.9	.348	-124.7
10.5	.681	-124.5	3.646	36.7	.085	5.9	.341	-133.5
11.0	.662	-130,3	3.534	31.1	.087	2.5	.331	-139.7
11.5	.633	-135.5	3.543	24.4	.088	7	.341	-147.8
12.0	.613	-139.7	3.467	18.9	.089	-3.0	.334	-155.1
12.5	.590	-144.2	3.459	12.9	.091	-6.5	.331	-162.1
13.0	.568	-149.0	3.432	7.2	.089	-10.1	.343	-168.6
13.5	.541	-153.8	3.436	.9	.092	-13.3	.343	-177.0
14.0	.536	-159.4	3.425	-4.8	.092	-16.8	.350	178.2
14.5	.508	-166.0	3.437	-11.4	.092	-20.3	.362	171.3
15.0	.487	-171.6	3.452	-17.9	.095	-24.1	.367	165.1
15.5	.471	180.0	3.483	-24.7	.095	-28.8	.378	159.8
16.0	.448	171.7	3.499	-31.5	.096	-33.7	.388	153.5
16.5	.433	164.0	3.486	-38.5	.096	-37.9	.394	147.2
17.0	.421	153.4	3.523	-46.0	.097	-43.9	.399	140.8
17.5	.399	143.1	3.537	-53.3	.094	-50.2	.399	135.1
18.0	.379	130.8	3.560	-61.8	.095	-56.1	.401	128.5



AMP. PARAMETER

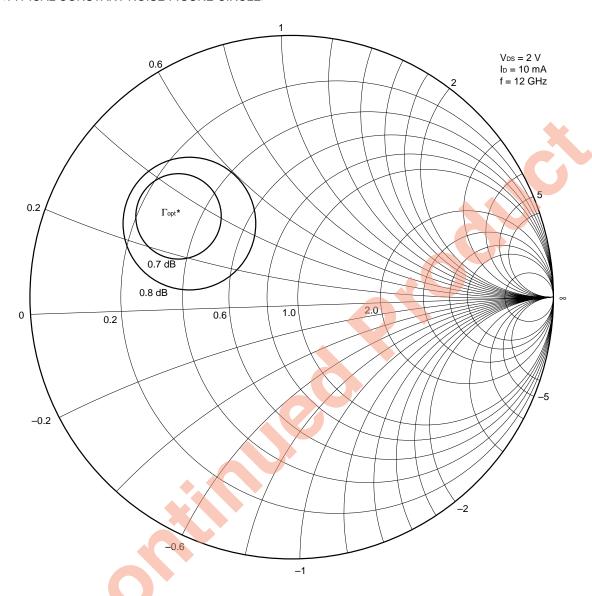
 $V_{DS} = 2 V$, $I_{D} = 10 mA$

FREQUENCY	GUmax.	GAmax.	S ₂₁ ²	S ₁₂ ²	K	Delay	Mason's U	G1	G2
GHz	dB	dB	dB	dB		ns	dB	dB	dB
2.0	31.08		13.31	-31.16	.12	.041		16.12	1.65
2.5	25.66		13.10	-29.25	.27	.041	31.919	10.98	1.58
3.0	25.49		13.09	-28.01	.26	.038	37.109	10.93	1.47
3.5	25.05		13.09	-27.01	.23	.036		10.61	1.35
4.0	23.38		13.06	-25.98	.31	.041		9.05	1.28
4.5	21.85		12.93	-25.12	.34	.038		7.79	1.13
5.0	21.58		12.74	-24.43	.34	.043		7.79	1.05
5.5	19.84		12.61	-23.83	.45	.038		6.25	.98
6.0	18.66		12.33	-23.20	.49	.043		5.47	.86
6.5	18.48		12.26	-22.99	.49	.036		5.39	.83
7.0	17.26		12.05	-22.49	.58	.032		4.43	.77
7.5	16.54		11.80	-22.25	.63	.034		4.05	.69
8.0	16.42		11.66	-22.02	.62	.037		4.10	.65
8.5	15.74		11.62	-22.05	.70	.029		3.50	.63
9.0	15.16		11.35	-21.74	.75	.038		3.22	.60
9.5	15.43		11.47	-21.56	.69	.031		3.40	.56
10.0	14.71		11.26	-21.37	.77	.033		2.89	.56
10.5	14.48		11.24	-21.44	.80	.039		2.71	.54
11.0	13.98		10.97	-21.23	.85	.031		2.51	.51
11.5	13.75		10.99	-21.09	.87	.037		2.23	.54
12.0	13.36		10.80	-20.99	.92	.030		2.04	.51
12.5	13.14		10.78	-20.80	.94	.033	41.799	1.86	.51
13.0	12.95		10.71	-20.98	.99	.032	27.081	1.69	.54
13.5	12.77	15.37	10.72	-20.70	1.00	.035	27.187	1.51	.55
14.0	12.73	15.26	10.69	-20.70	1.01	.032	28.158	1.47	.57
14.5	12.63	14.66	10.72	-20.71	1.03	.037	26.287	1.29	.61
15.0	12.57	14.68	10.76	-20.42	1.02	.036	27.862	1.18	.63
15.5	12.60	14.67	10.84	-20.47	1.03	.038	27.895	1.09	.67
16.0	12.56	14.53	10.88	-20.39	1.03	.038	27.180	.97	.71
16.5	12.48	14.37	10.85	-20.34	1.04	.039	26.314	.90	.73
17.0	12.54	14.56	10.94	-20.24	1.03	.042	27.747	.85	.75
17.5	12.48	14.01	10.97	-20.54	1.08	.040	23.317	.75	.75
18.0	12.46	13.93	11.03	-20.48	1.09	.047	22.734	.67	.76



NOISE PARAMETER

<TYPICAL CONSTANT NOISE FIGURE CIRCLE>



<NOISE PARAMETER>

 $V_{DS} = 2 \text{ V}, I_{D} = 10 \text{ mA}$

Freq.	NFmin.	Ga	Γ	R₀/50	
(GHz)	(dB)	(dB)	MAG.	ANG. (deg.)	Kn/30
2.0	0.29	20.0	0.85	20	0.30
4.0	0.30	18.3	0.75	41	0.28
6.0	0.31	16.5	0.68	63	0.20
8.0	0.34	15.0	0.61	86	0.13
10.0	0.37	13.6	0.56	111	0.09
12.0	0.40	12.5	0.52	137	0.05
14.0	0.49	12.0	0.47	164	0.04
16.0	0.63	11.8	0.40	-168	0.04
18.0	0.81	11.5	0.31	-139	0.07



RECOMMENDED SOLDERING CONDITIONS

The following conditions (see table below) must be met when soldering this product.

Please consult with our sales offices in case other soldering process is used, or in case soldering is done under different conditions.

<TYPES OF SURFACE MOUNT DEVICE>

For more details, refer to our document "SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL" (C10535E).

Soldering process	Soldering conditions		Symbol
Infrared ray reflow	Peak package's surface temperature: 230 °C or below, Reflow time: 30 seconds or below (210 °C or higher), Number of reflow process: 1, Exposure limit Note: None		IR30-00
Partial heating method	Terminal temperature: 230 °C or below, Flow time: 10 seconds or below, Exposure limit Note: None	~,(C)	

Note Exposure limit before soldering after dry-pack package is opened.

Storage conditions: 25 °C and relative humidity at 65 % or less.

Caution Do not apply more than a single process at once, except for "Partial heating method".

PRECAUTION Avoid high static voltage and electric fields, because this device is Hetero Junction field effect transistor with shottky barrier gate.

Caution

The Great Care must be taken in dealing with the devices in this guide.

The reason is that the material of the devices is GaAs (Gallium Arsenide), which is designated as harmful substance according to the law concerned.

Keep the law concerned and so on, especially in case of removal.

[MEMO]



[MEMO]



[MEMO]



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Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots

Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)

Specific: Aircrafts, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

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